Kulicke & Soffa Launches New IConnPS ProCu PLUSTM And IConnPS ProCu PLUSTM LA Copper Wire Bonders

For Copper Today, PLUS Tomorrow

SINGAPORE--(BUSINESS WIRE)-- Kulicke & Soffa Industries, Inc. (NASDAQ: KLIC) ("K&S") today announced another extension of its highly successful K&S Power SeriesTM. The Company's new Copper Wire Bonders, IConn*PS* ProCu *PLUSTM* andIConn*PS* ProCu *PLUSTM* LA, with proprietary upgraded and enhanced subsystems, is engineered to handle even the most challenging, leading edge copper bonding demands.

The new IConn*PS* ProCu *PLUSTM* andIConn*PS* ProCu *PLUSTM* LA Copper Wire Bonders come with the new ProCu5 process, which offers the highest level of Copper Process capability. The ProCu5 process enables robust copper wire bonding production for advanced wafer nodes below 28 nanometer.

The IConn*PS* ProCu *PLUSTM* Copper Wire Bonder offers the standard 80mm bondable area with field upgradeability to an 87mm option. The IConn*PS* ProCu *PLUSTM* LA model comes with a factory configured bondable area of 87mm.

Nelson Wong, Kulicke & Soffa's Vice President, Wire Bond Solutions Business Unit, remarked, "Customers can rely on K&S in helping meet the process challenges of copper wire bonding at advanced silicon nodes. As the global leader of the wire bond industry, K&S is committed to providing our customers with reliable, cutting-edge technology solutions that add value to their businesses. Our R&D team continues to innovate and develop new process techniques to improve portability, stability and reliability, offering our customers a cost of ownership advantage and high confidence in our products."

The IConn*PS* ProCu *PLUSTM* LA Copper Wire Bonder will debut at the Semicon Taiwan show at the Taipei World Trade Center Nangang Exhibition Hall from September 4-6, 2013.

About Kulicke & Soffa

Kulicke & Soffa (NASDAQ: KLIC) is a global leader in the design and manufacture of semiconductor and LED assembly equipment. As a pioneer in this industry, K&S has provided customers with market leading packaging solutions for decades. In recent years, K&S has expanded its product offerings through strategic acquisitions, adding wedge bonding and a broader range of expendable tools to its core ball bonding products. Combined with its extensive expertise in process technology, K&S is well positioned to help customers meet the challenges of assembling the next-generation semiconductor and LED devices. (www.kns.com)

Kulicke & Soffa Industries, Inc.
Sheila Frese
Public Relations

P: +1-949-660-0440
F: +1-949-660-0444
sfrese@kns.com
or
Joseph Elgindy
Investor Relations & Strategic Planning
P: +1-215-784-7518
F: +1-215-784-6180
jelgindy@kns.com
or
Global IR Partners
David Pasquale
P: +1-914-337-8801
klic@globalirpartners.com

---

https://investor.kns.com/2013-08-29-Kulicke-Soffa-Launches-New-IConnPS-ProCu-PLUSTM-And-IConnPS-ProCu-PLUSTM-LA-Copper-Wire-Bonders